

The Silicon Vertex Detector of the Belle II Experiment

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Outline

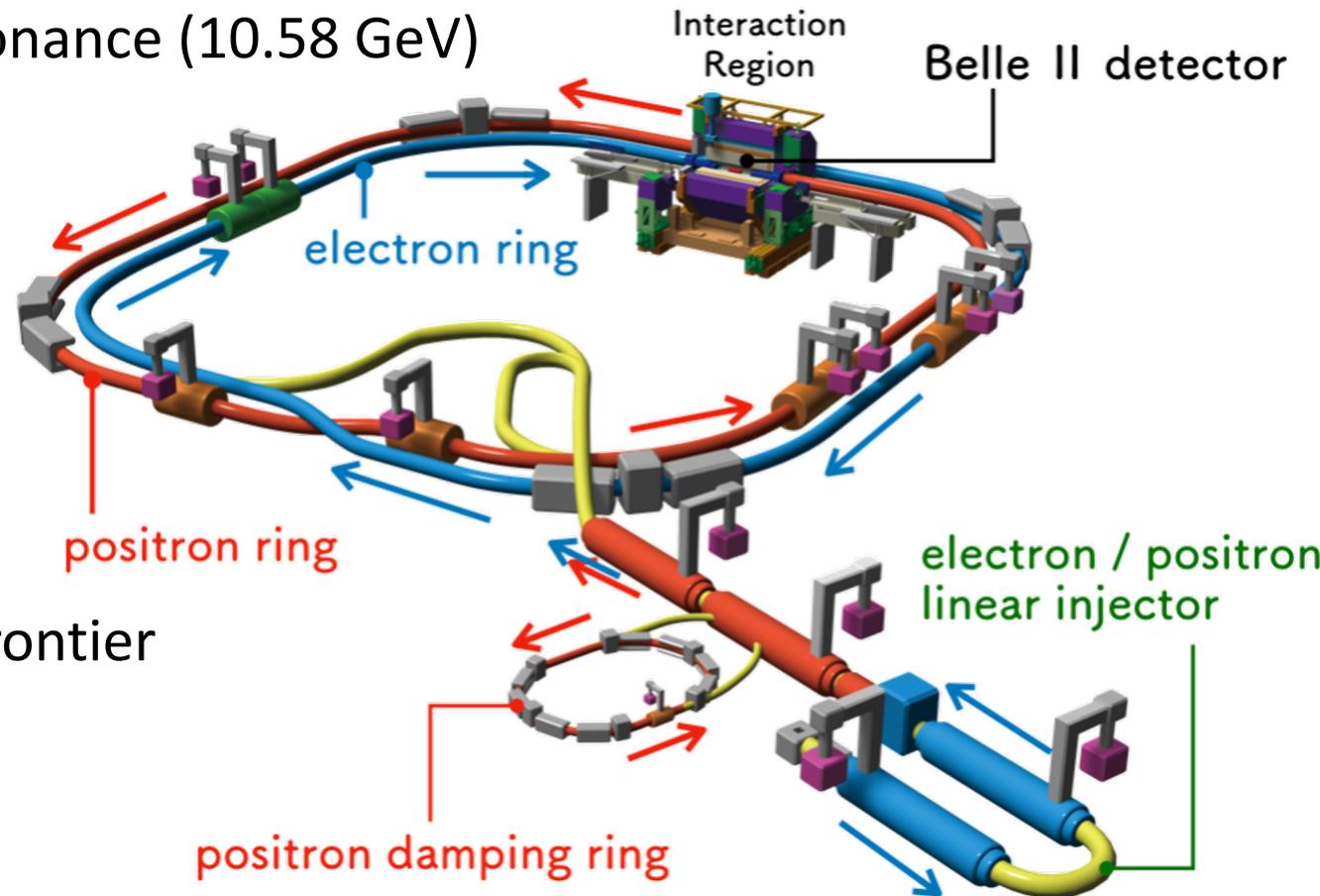
- ◆ Introduction
- ◆ Operation & Performance
- ◆ Beam background & Radiation effect
- ◆ Conclusions

Introduction

Belle II/SuperKEKB

◆ SuperKEKB: dedicated accelerator for Belle II

- Asymmetric e^+e^- collisions at $\Upsilon(4S)$ resonance (10.58 GeV)
- Target integrated luminosity: 50 ab^{-1}
- Target instantaneous luminosity:
 $\sim 6 \times 10^{35} \text{ cm}^{-2}\text{s}^{-1}$
- Current record: $3.1 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$



◆ Belle II

- New physics search at the luminosity frontier
- Accumulated 213 fb^{-1} data
- Essentials for physics programs:
 - Precise determination of decay vertices
 - Low momentum tracking
 - Good particle identification

Belle II Vertex Detector

◆ Requirements

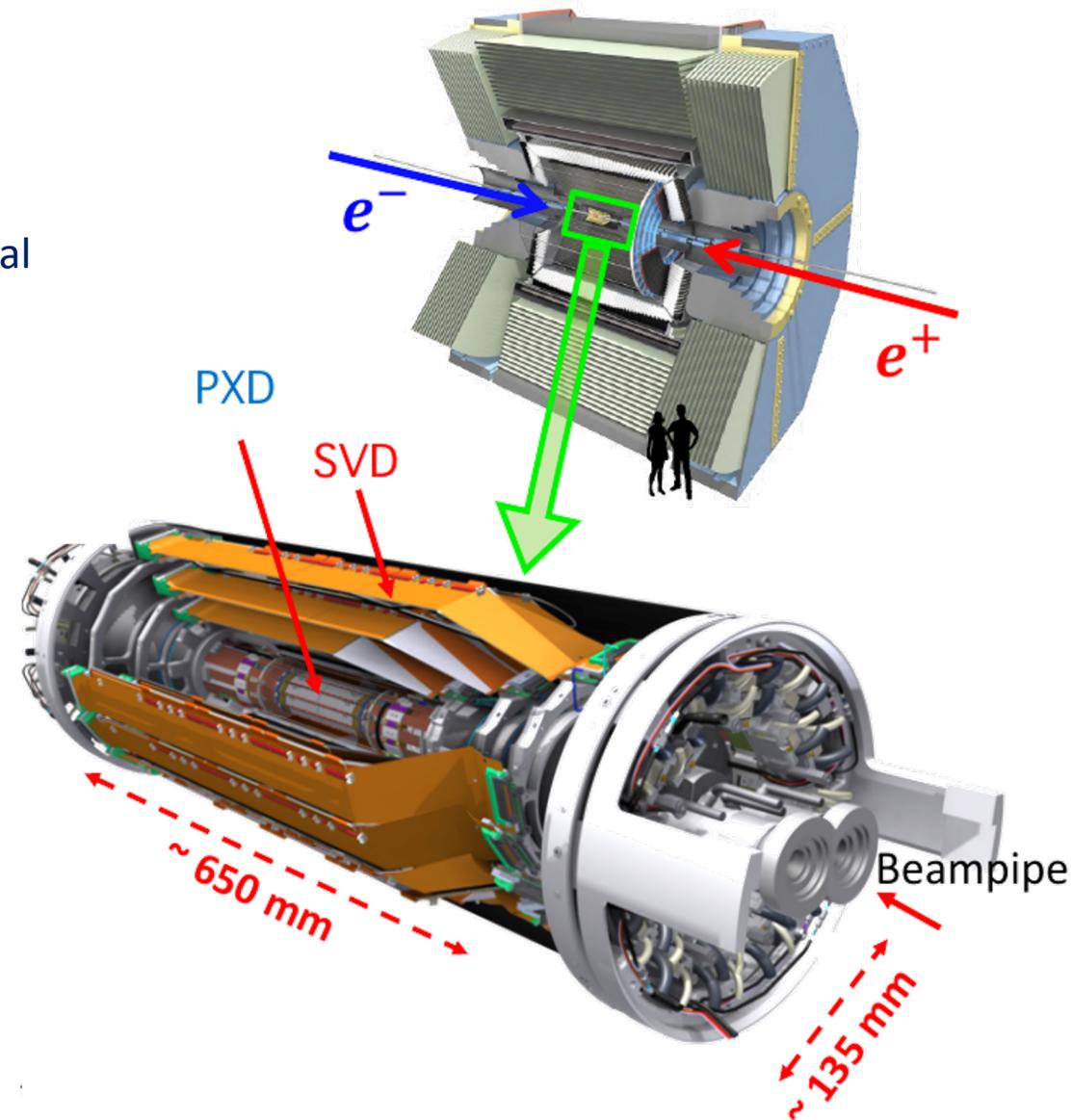
- Better vertex resolution with respect to Belle to compensate reduced Lorentz boost
 - improved point resolution/reduced inner radius/lower material
- Operate in high background environment
 - Hit rates: 20-3 MHz/cm² @R=14-40mm
- Radiation hard
 - 2-0.2 Mrad/yr @ R = 14-40 mm

◆ Pixel Detector (PXD)

- DEPFET pixel sensors: layer-1-2
- Innermost layer 1.4 cm from interaction point

◆ Silicon Vertex Detector (SVD)

- Double-sided Si strip sensors: layer-3-4-5-6
- Low material budget: 0.7% X_0 per layer



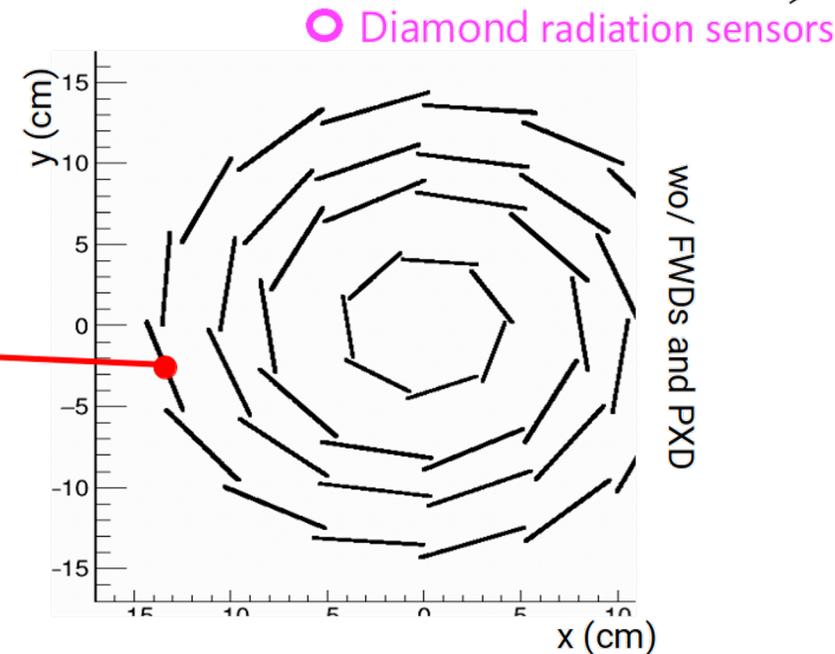
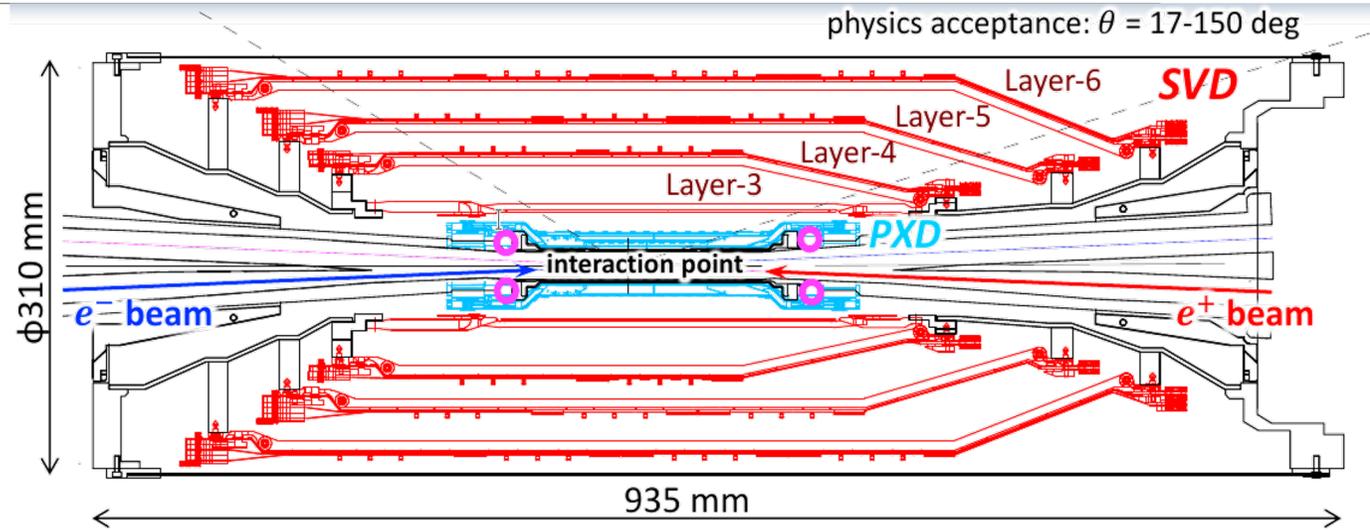
The Silicon Vertex Detector (SVD)

◆ SVD Roles

- Extrapolate tracks to PXD
 - essential for reconstruction of decay vertices
 - PXD region of interest for data reduction
- Stand-alone tracking for low p_T tracks
- Precise vertexing of K_S
- PID with dE/dx

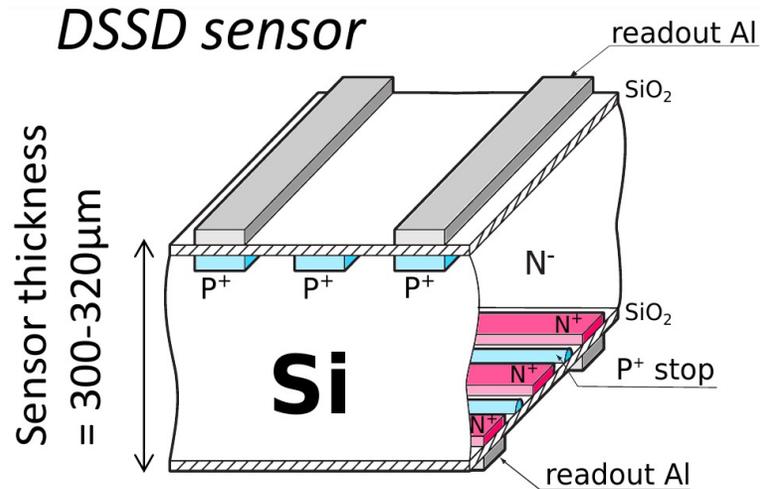
◆ Diamond sensors

- placed on the beam pipe
- for radiation monitor and beam abort

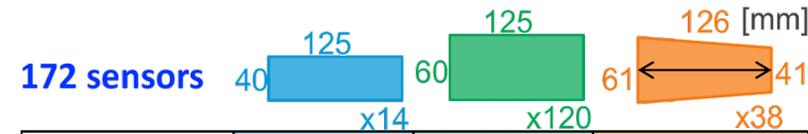
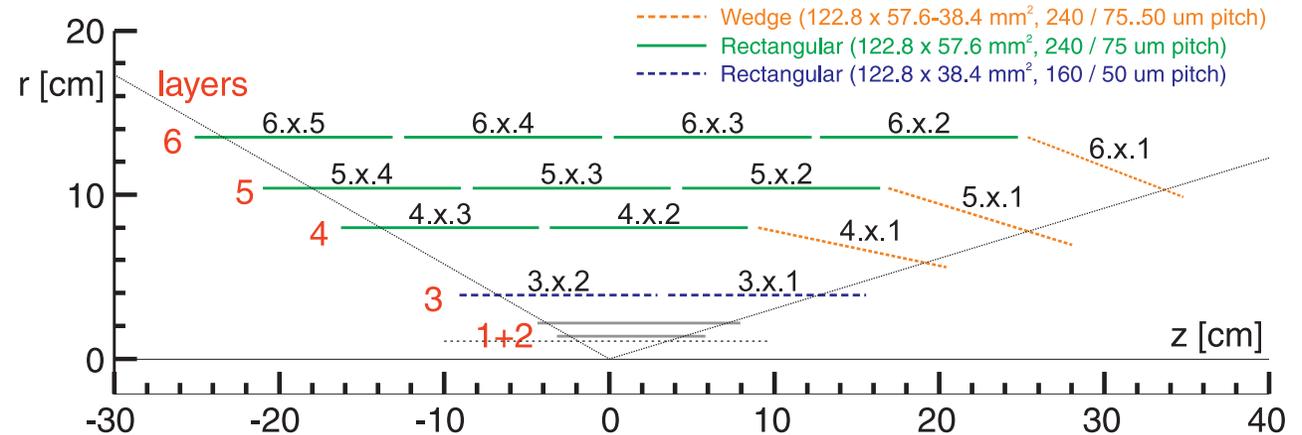
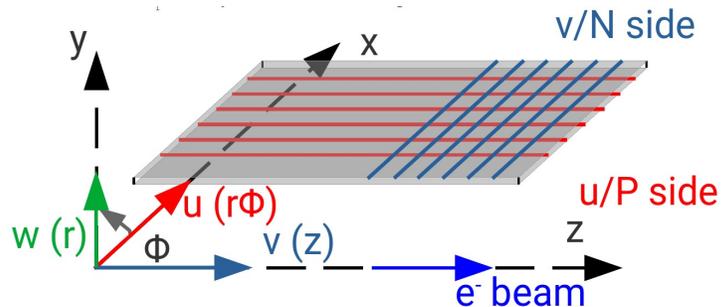


SVD: Double-sided Silicon Strip Detector

◆ Provide 2-D spatial information



AC-coupled strips on N-type substrate
 Full depletion voltage: 20-60V
 Operation voltage: 100V



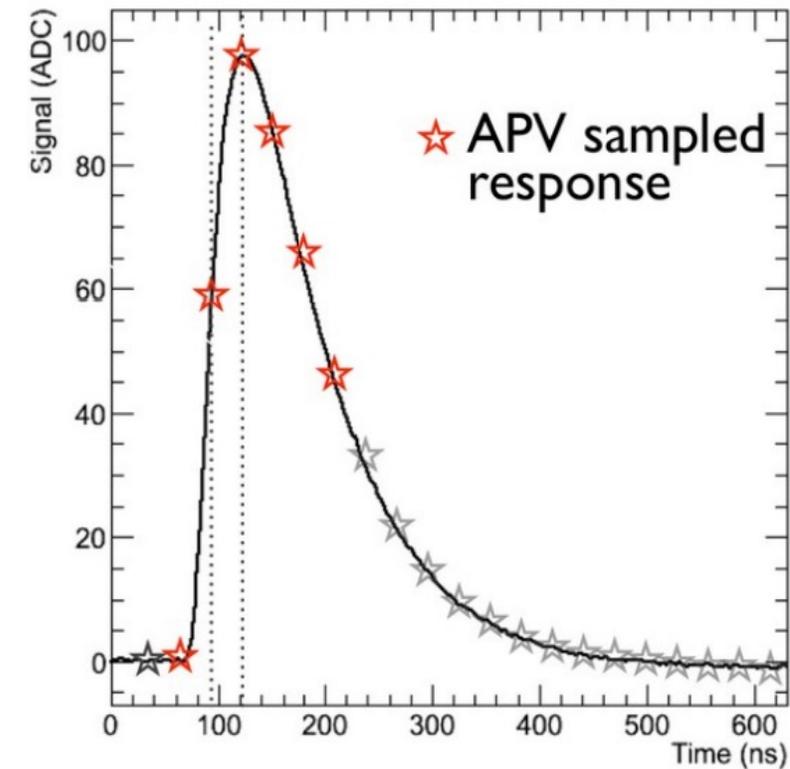
	Small	Large	Trapezoidal
# of p-strips*	768	768	768
p-strip pitch*	50 μm	75 μm	50-75 μm
# of n-strips*	768	512	512
n-strip pitch*	160 μm	240 μm	240 μm
thickness	320 μm	320 μm	300 μm
manufacturer	HPK		Micron

*readout strips – one floating strip on both sides

◆ Total: 172 sensors, 1.2 m² sensor area and 224k readout strips

Front-end ASIC: APV25

- Originally developed for CMS silicon tracker
- Fast: 50 ns shaping times
- Radiation hard: > 100 Mrad
- Power consumption: 0.4 W/chip (700 W in total)
- 128 channel inputs per chip
- Operated in “multi-peak” mode @ ~32 MHz
 - Bunch-crossing frequency ~8*32 MHz, clock not synchronous with them as in CMS
 - 6 subsequent samples recorded (3-sample also possible)
- 3/6-mixed acquisition mode prepared for higher luminosity
 - To reduce the dead time/data size/background hit occupancy
 - Switching sampling number according to the timing precision of trigger
 - The functionality already tested in the real setup and confirmed to work
- ◆ 3-sample DAQ mode: only 3 subsequent samples recorded
 - half time-window → less background occupancy
 - halve APV25 FIFO usage → reduce dead-rate
 - → data-size reduced to less than a half

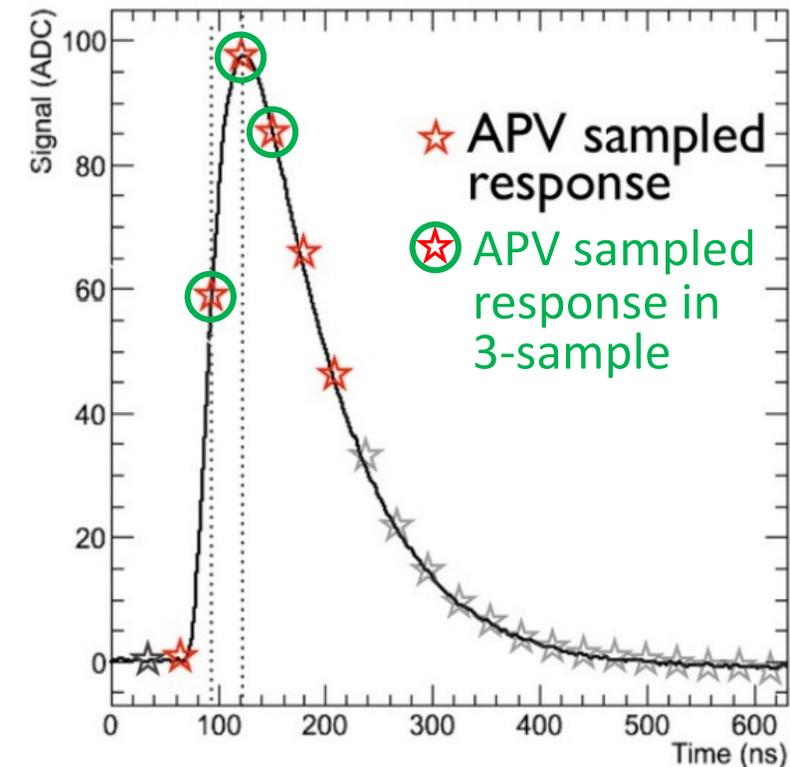


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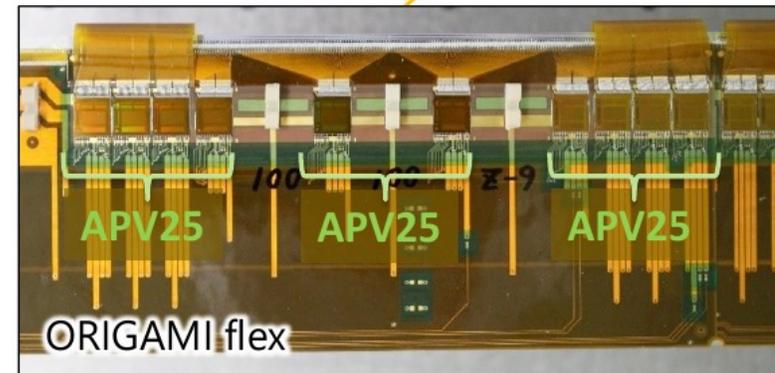
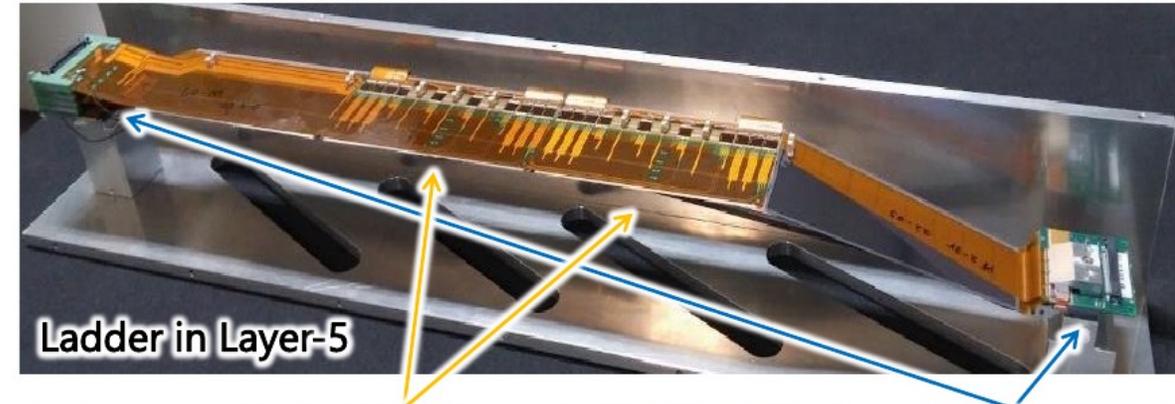
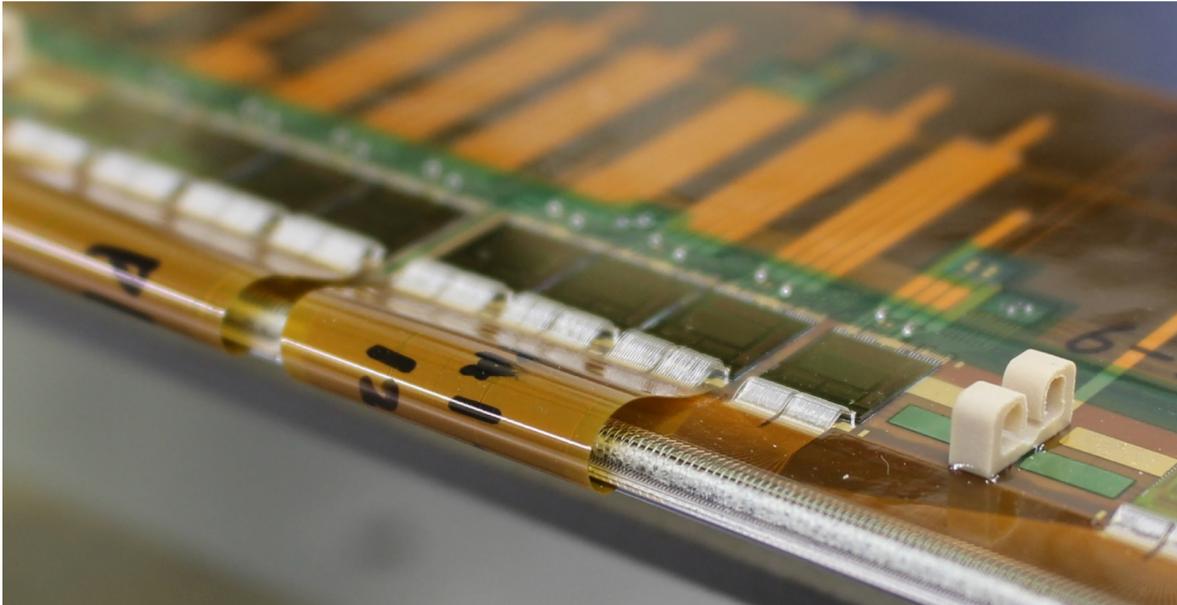
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Origami chip on sensor concept

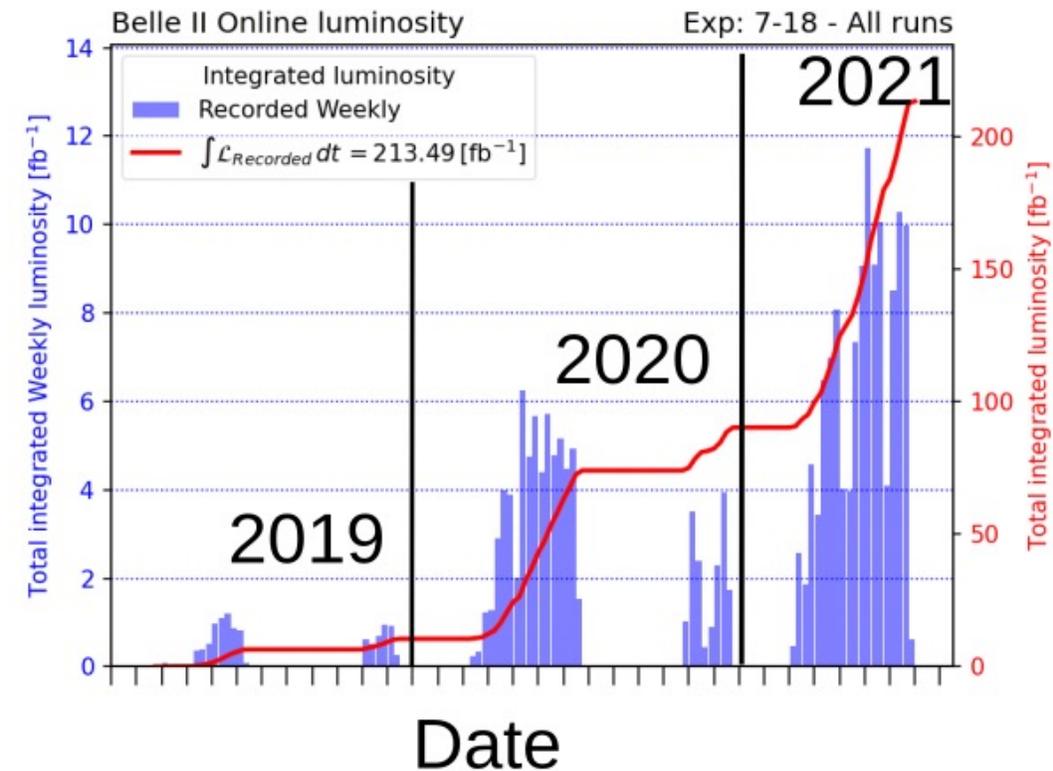
- ◆ Readout chips directly on each middle sensor
 - shorter signal propagation length (smaller capacitance and noise)
 - Thinned to 100 μm to reduce material budget
 - Wrapped flex to read both sides from the same side
 - Cool only one side with bi-phase $-20\text{ }^{\circ}\text{C}$ CO_2



Operation & Performance

Operational experience

- ◆ SVD installed in 2018, operated since 2019
- ◆ Reliable and smooth operation without major problems
 - Total fraction of masked strips $\sim 1\%$
 - One APV25 chip disabled in spring 2019 (out of 1748)
→ fixed by cable reconnection in summer 2019
- ◆ Excellent detector performance
 - hit efficiency stably $> 99\%$ in most of the sensors



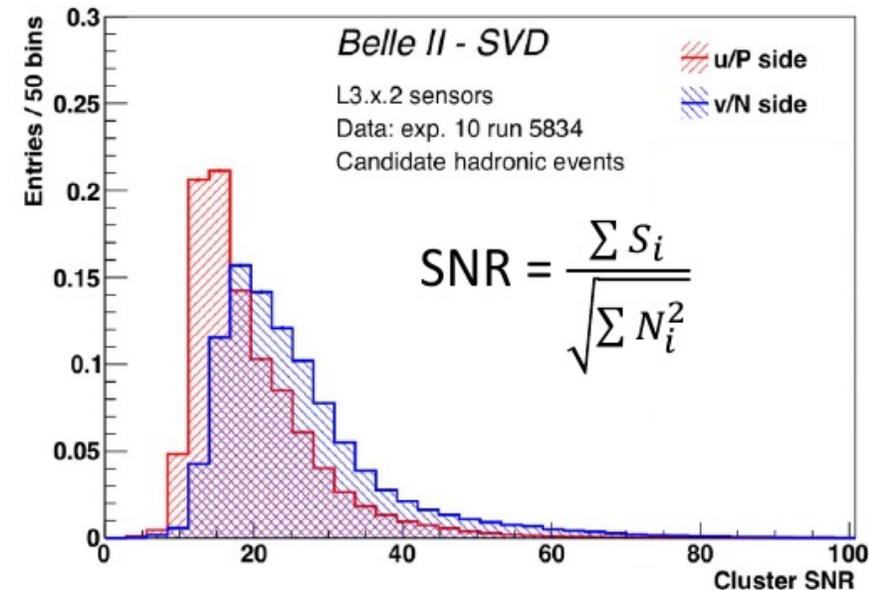
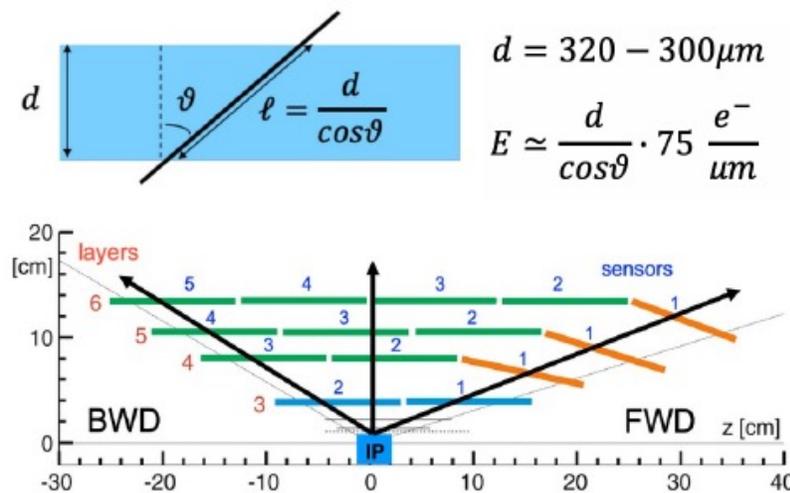
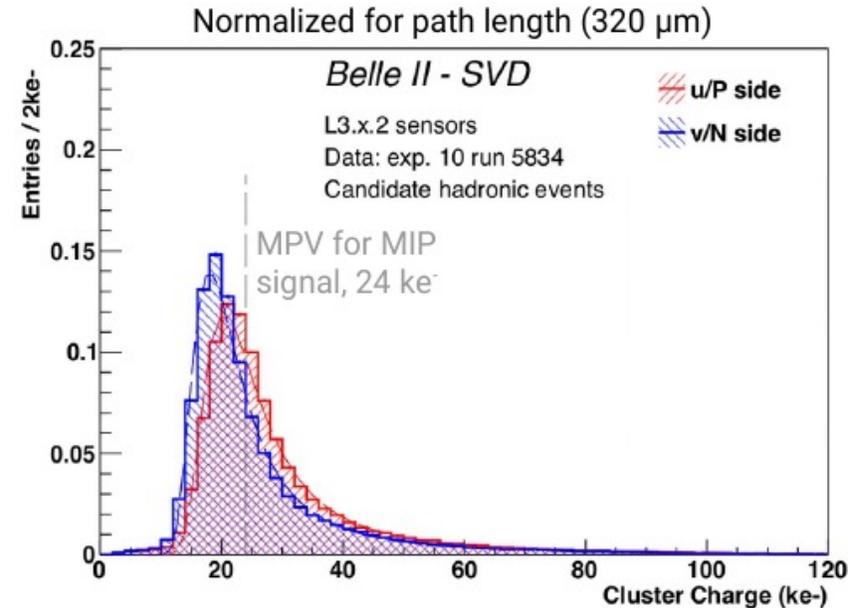
Signal charge and signal-to-noise ratio

◆ Signal charge: normalized for the track path length in silicon

- **u/P side**: agree with MIP considering $\sim 15\%$ uncertainty in APV25 gain calibration
- **v/N side**: 10-30% signal loss due to large pitch and presence of floating strip
 - similar in all sensors

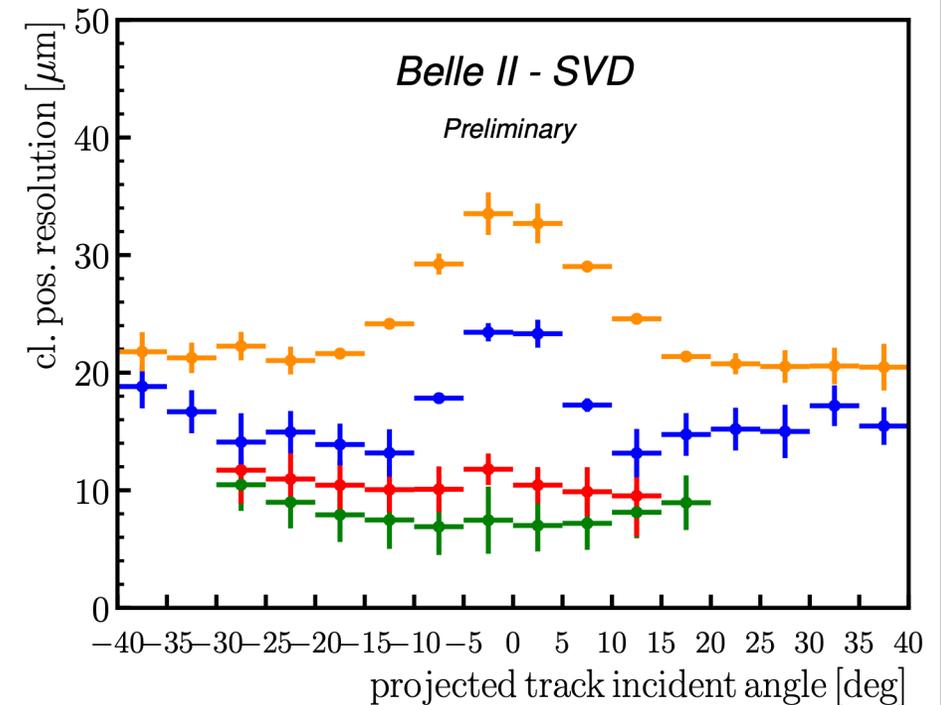
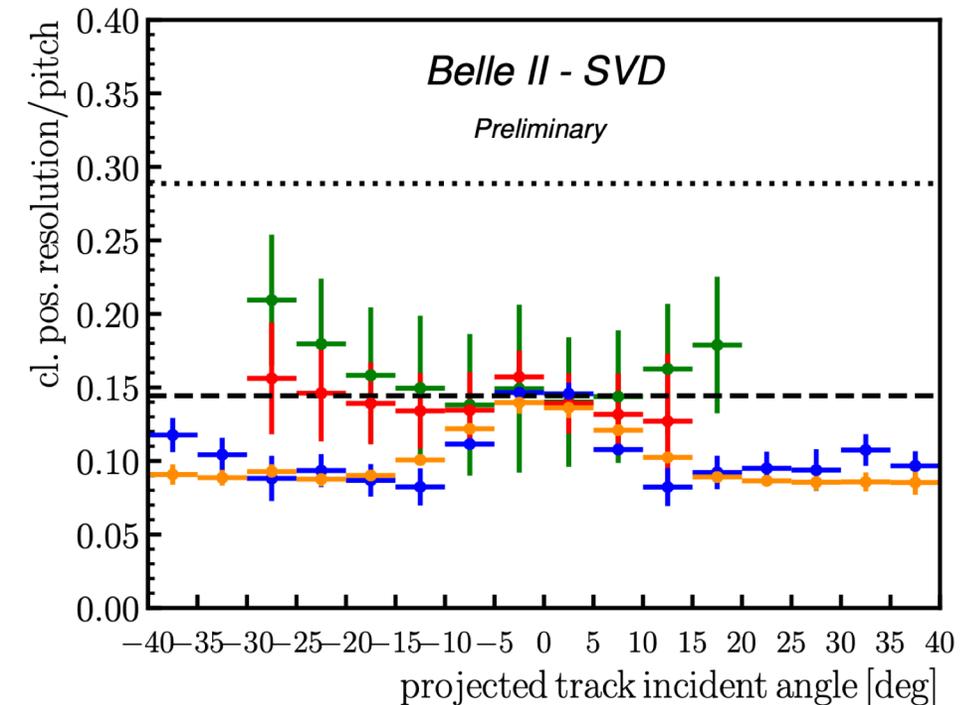
◆ SNR: very good in all sensors (most probable value: 13-30)

- **u/P side**: larger noise due to longer strip length (larger inter-strip capacitance)



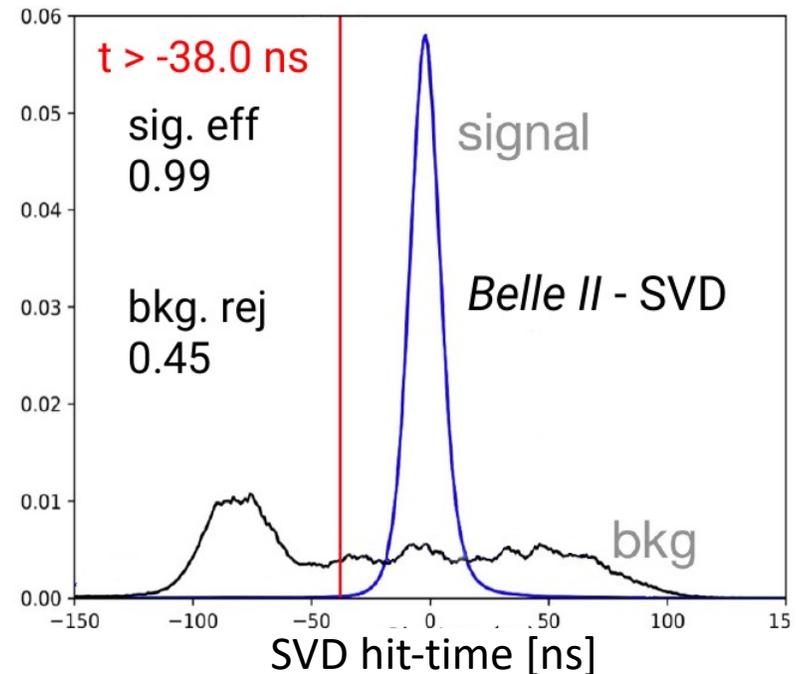
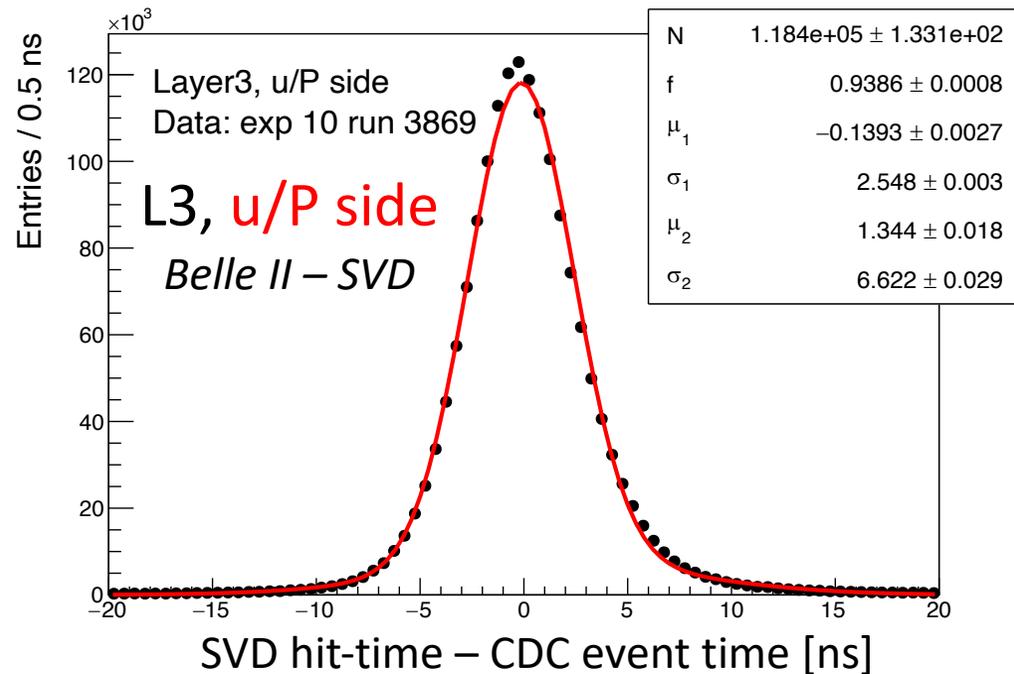
Cluster position resolution

- ◆ Preliminary cluster position resolution measured on $e^+e^- \rightarrow \mu^+\mu^-$ data
 - Estimated from the residual of the cluster position with respect to the track (unbiased)
 - Effect of the track extrapolation error subtracted
 - Excellent position resolution in agreement with the expectations from the pitch
 - Still room for improvement for the u/P side (work ongoing)



Hit-time resolution

- ◆ Excellent hit-time resolution with respect to event time
 - event time estimated by central drift chamber (CDC) outside of SVD
 - (~ 2.9 ns u/P, ~ 2.4 ns v/N)
- ◆ Possible to efficiently reject off-time background hits
 - Will be used for higher luminosity and background levels



3-sample acquisition mode

◆ performance

■ ideal 3 samples provide enough information as 6 samples

- amplitude – peak ADC sample
- hit-time – rising edge of the waveform

■ degrades if the trigger jitter is large

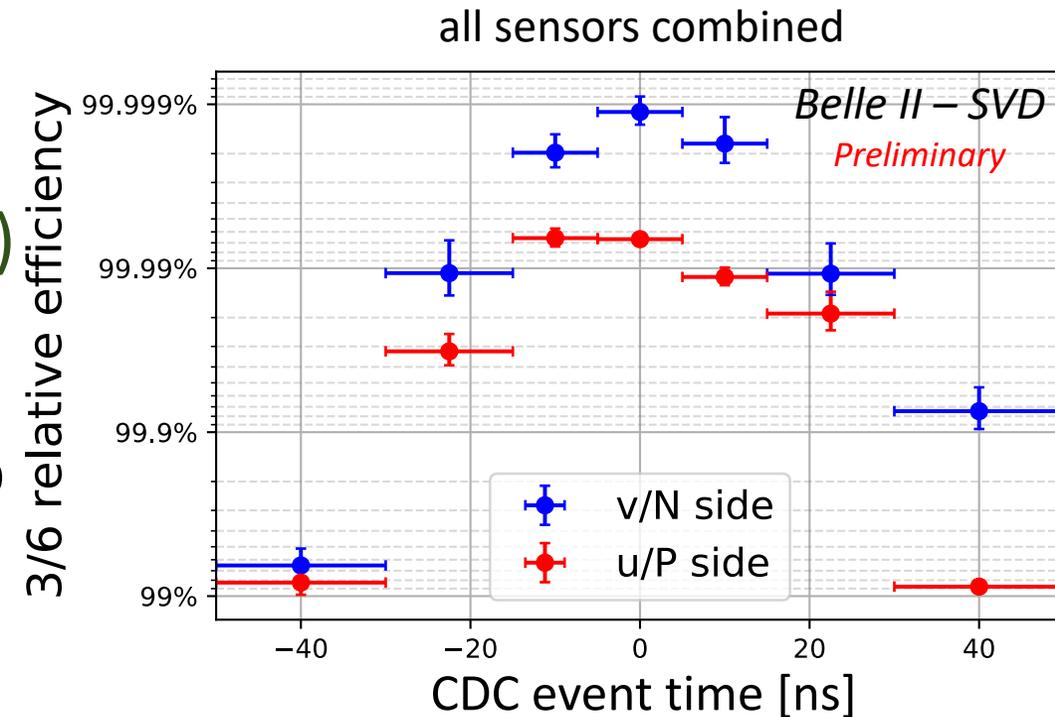
◆ 1st step: efficiency (compared to 6-sample)

■ emulate 3-sample mode offline using trigger timing information

■ efficiency based on track using CDC, SVD and PXD

■ > 99.9% for trigger jitter less than 30 ns

- almost a whole clock-cycle



Beam background & Radiation effect

Beam background

◆ Beam background increases SVD hit occupancy which degrades tracking performance

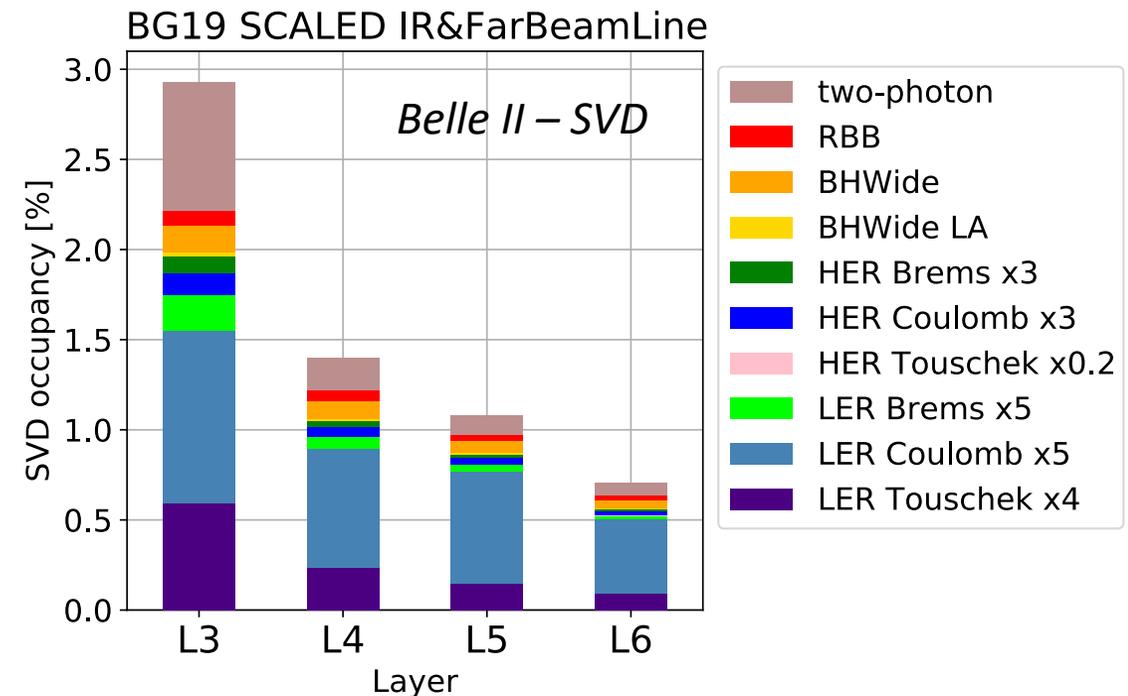
■ Present occupancy limit in layer-3: ~ 3%

- up to $\times 2$ will be allowed using hit-time to reject background

■ With current luminosity, average hit occupancy in layer-3 is well under control (< 0.5%)

■ Projection of hit occupancy at $L = 8 \times 10^{35} \text{ cm}^{-2} \text{ s}^{-1}$ is about 3% in layer-3

- estimated by scaling MC with data/MC ratio
- correspond to dose of ~ 0.2 Mrad/smy (smy = 10^7 s)
 - = 1-MeV neutron fluence of ~ $5 \times 10^{11} \text{ n}_{\text{eq}}/\text{cm}^2/\text{smy}$
- Long term BG extrapolation affected by large uncertainties
 - collimation
 - injection BG (still not included)



Integrated dose

◆ SVD dose estimated by dose on diamond sensors: 60 krad in layer-3 mid plane (the most exposed to radiation)

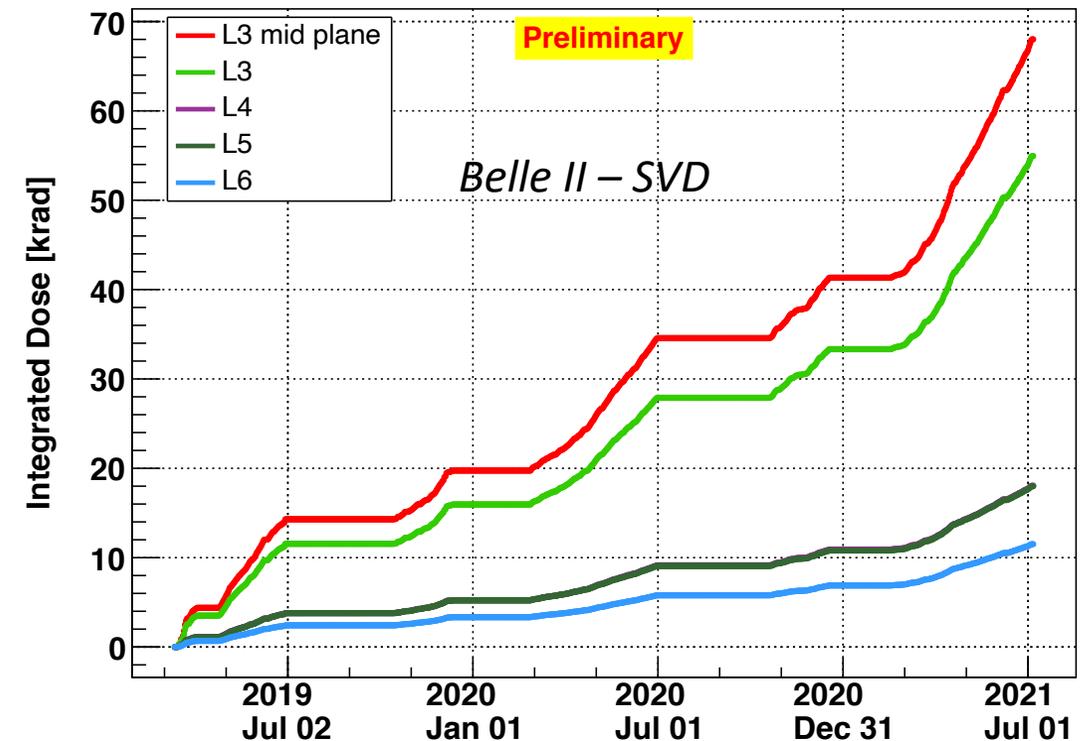
- Dose estimate based on correlation between SVD occupancy and diamonds dose
- Several assumptions and large uncertainty (~ 50%)

◆ 1-MeV equivalent neutron fluence:

$\sim 1.6 \times 10^{11} \text{ n}_{\text{eq}}/\text{cm}^2$ in first 2.5 years

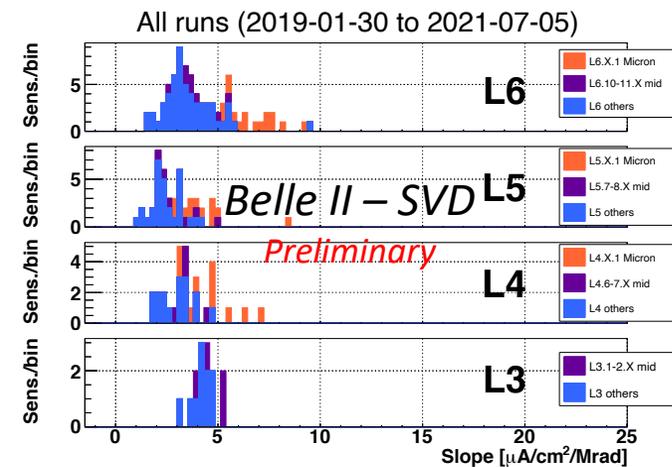
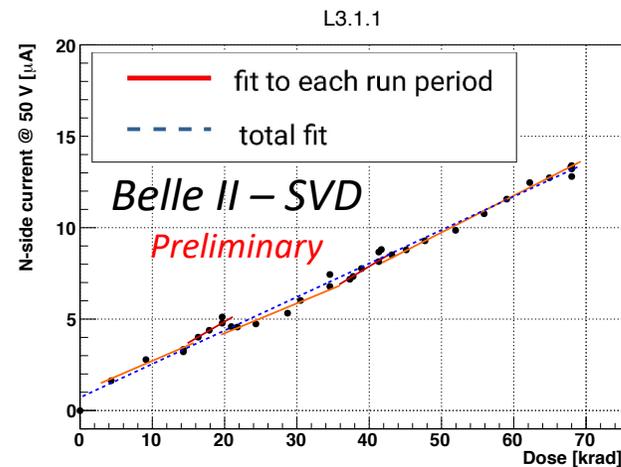
- assuming dose/neq fluence ratio
= $2.3 \times 10^9 \text{ n}_{\text{eq}}/\text{cm}^2/\text{krad}$ from MC)

Int. dose in SVD - New coeff. (from exp. 12 & 16) + EODB correction (from 14/2102)



Radiation effect on leakage current

- ◆ Good linear correlation between leakage current and estimated dose
 - Slope: 2-5 $\mu\text{A}/\text{cm}^2/\text{Mrad}$ with large variations due to temperature effects and dose spread among sensors in layer (average dose in layer used in estimate)
 - Same order of magnitude as BaBar measurement (1 $\mu\text{A}/\text{cm}^2/\text{Mrad}$ @ 20 °C) [NIMA 729, 615-701, 2013]
- ◆ Even after 10 Mrad irradiation, leakage current will not significantly affect strip noise
 - Noise dominated by sensor capacitance because of short shaping time (50ns) in APV25



Radiation effect on strip noise

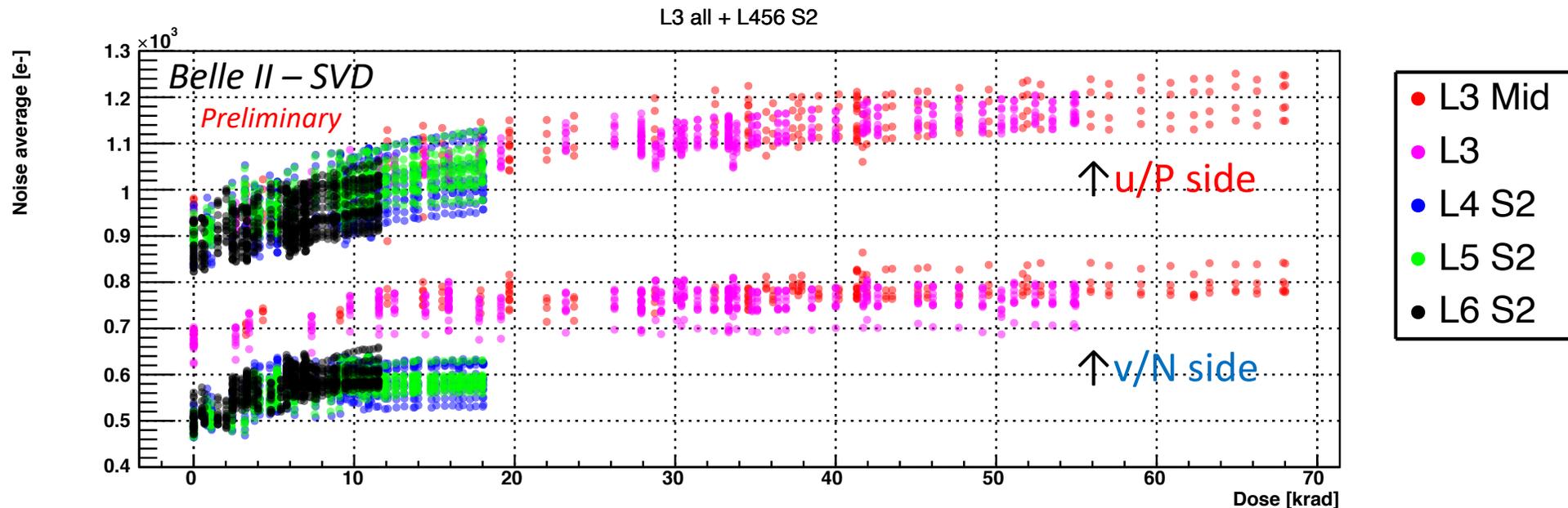
◆ Noise increase of 20-25% in layer-3

■ Not affecting performance

■ Likely due to radiation effects on sensor surface

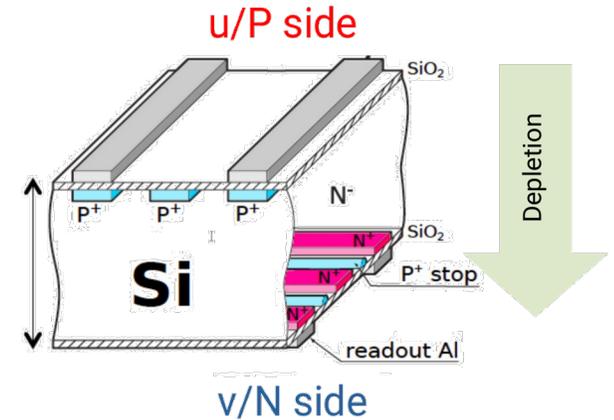
- Non-linear increase due to fixed oxide charges that increase inter-strip capacitance,
- expected to saturate

■ Saturation seen on v/N side and starting to be seen on u/P



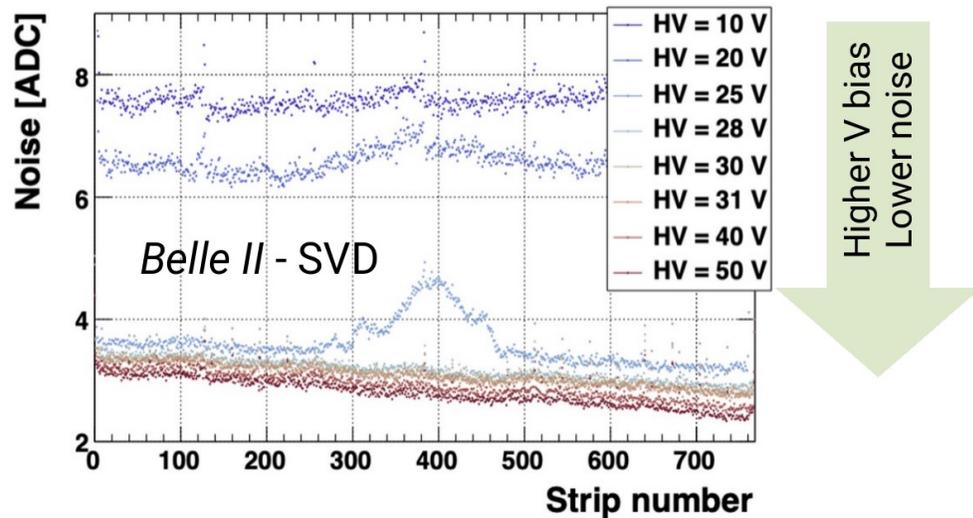
Radiation effect on depletion voltage

- ◆ Minimum of v/N side strip noise at full depletion
 - v/N side insulated only when the n-type bulk is fully depleted
 - Over-depletion bias still slightly decrease noise
 - reduce electron accumulation layer on n-side surface

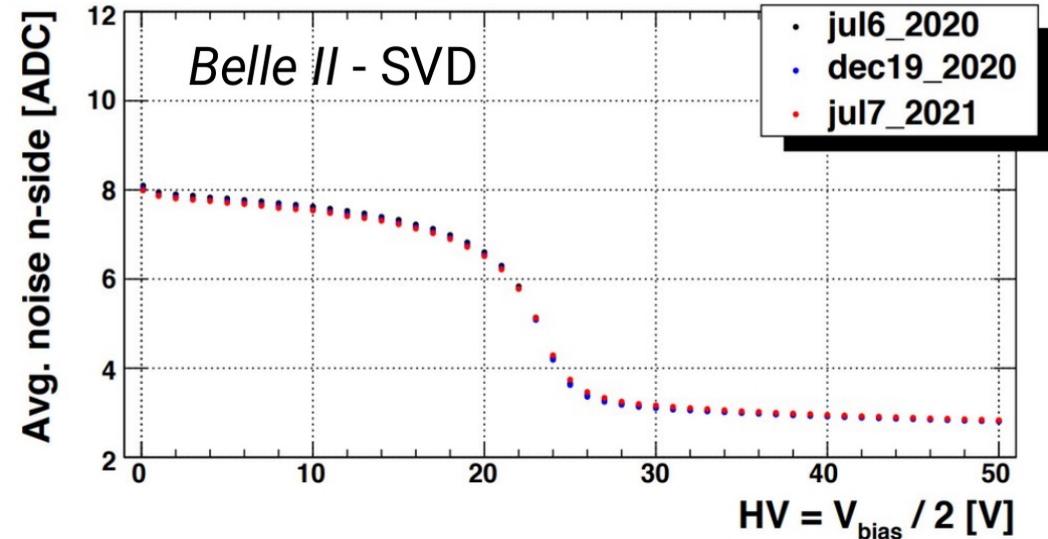


- ◆ No change in full depletion voltage observed with time: consistent with low integrated neutron fluence ($\sim 1.6 \times 10^{11} \text{ n}_{\text{eq}}/\text{cm}^2$)

L3.5.1 v/N Side - Strip Noise



L3.5.1 N Side - Noise



Conclusions

- ◆ SVD has been taking data in Belle II since March 2019 smoothly and reliably
- ◆ Excellent performance in agreement with expectations
 - Still some room for improvement in cluster position resolution
- ◆ Seen first effects of radiation damage at the expected level but not affecting performance
- ◆ Ready to cope with increased beam background
 - Reject off-time background using hit-time
 - 3/6-mixed acquisition mode to reduce dead time, data size and occupancy